

ABSTRACT

A method for producing a semiconductor device is obtained by encapsulating a semiconductor element by an encapsulating sheet. The method for producing a semiconductor device includes the steps of preparing the encapsulating sheet and the semiconductor element; after the preparing step, encapsulating the semiconductor element by the encapsulating sheet; and after the encapsulating step, collecting the encapsulating sheet and the semiconductor element. The encapsulating step includes an excess portion occurring step of allowing an excess portion in the encapsulating sheet to occur, while the encapsulating sheet is pressed between two pressing members disposed in opposed relation to each other by sandwiching the encapsulating sheet therebetween. The collecting step includes a removing step of removing the excess portion.